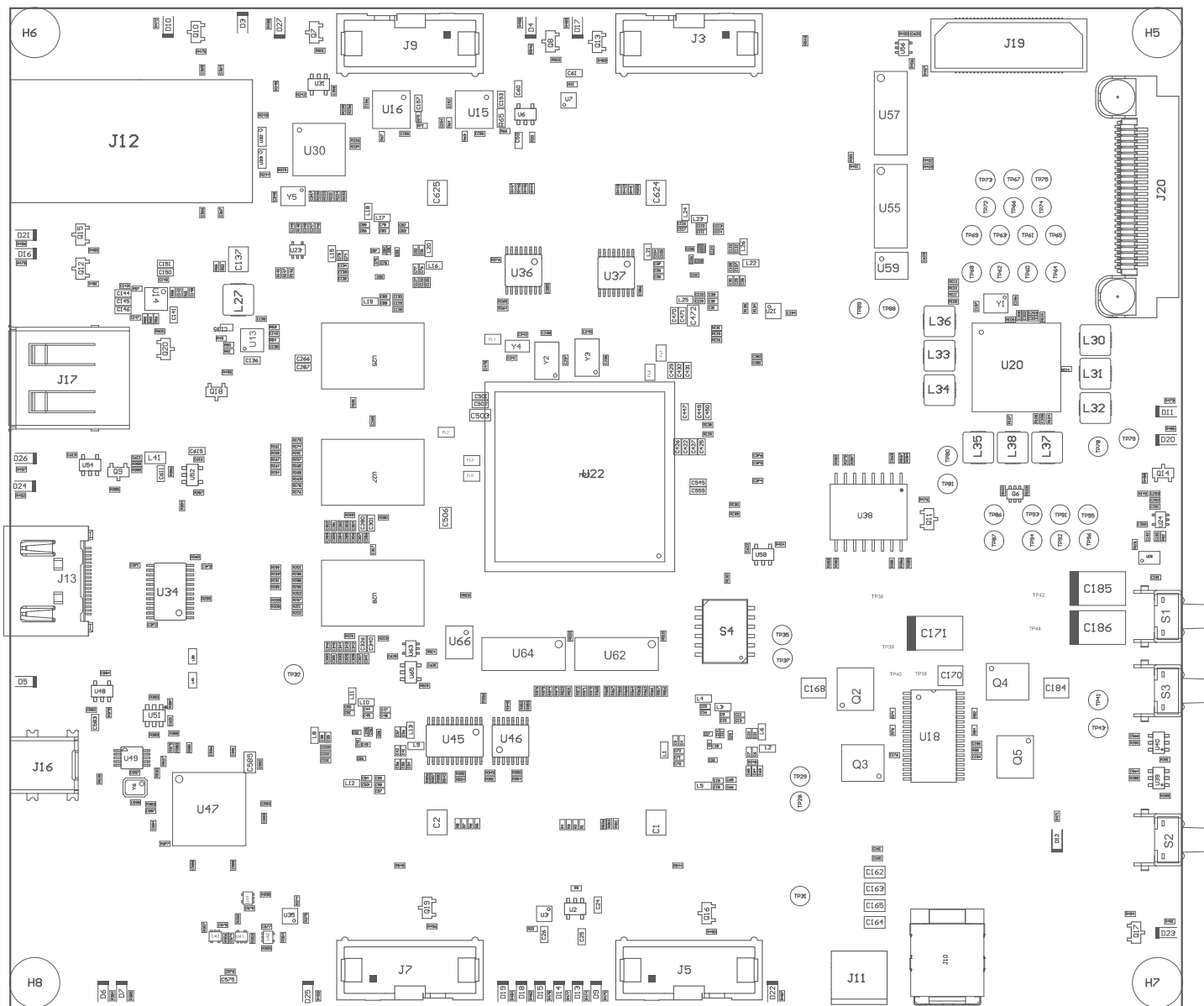


Z22 ■ These assemblies are ESD sensitive, ESD precautions shall be observed.
 Z23 ■ These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
 Z24 ■ These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.
 Z25 ■ INDICATION FOR COMPONENTS D* (WITH 2 PINS) ARE GIVEN AT THEIR CATHODE SIDE.
 Z26 ■ MPI must be soldered down to the Top Layer of PCB.
 Z27 ■ Refer to Test Procedure Document for installing uSD, H9, and SSD Drive



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE	BOARD #: PROC055	REV: A	SUN REV: Not In VersionControl
	TID #: N/A		
PLOT NAME = Top Assembly Drawing	GENERATED : 10/22/2021 11:27:57 AM	TEXAS INSTRUMENTS	



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE	BOARD #: PROC055	REV: A	SUN REV: Not In VersionControl
	TID #: N/A		
PLOT NAME = Bottom Assembly Drawing	GENERATED : 10/22/2021 11:27:58 AM	TEXAS INSTRUMENTS	